S-Sn99Cu1 (LC99M1)

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1. General characteristics

S-Sn99Cu1 solder manufactured in the first melt of tin and copper according to PN EN 29453:2000 standard in continuous casting process in air-free environment; afterwards extruded, in order to eliminate oxide occurrence.

2. Chemical characteristics

2.1 Tin contents: rest

2.2 Copper contents: 0,45% to 0,9%

2.3 Copper contents: 99,90%

2.4 Max. impurities:

Cu	Pb	Cd	Sb	Bi	Fe	Zn	Al	As	other
-	0,10%	0,002%	0,05%	0,10%	0,02%	0,001%	0,001%	0,03%	0,08%

3. Physical characteristics

3.1 Melting point: 230°C to 240°C

3.2 Density: 7,30 g/cm^3

3.3 Assortment:
- rods,
- bars,
- wires with or without flux from 0,25 mm to 5,00 mm diameters

3.4 Working temperature: 300°C to 380°C

4. Usage

S-Sn99Cu1 solder is primarily used in electronics industry, for manufacturing of electronic devices and components, bath soldering of printed circuits, electrotechnics and precision soldering of electrical components in mechanical engineering, as well as in soldering of components plated with tin, tin-lead, cadmium, zinc and silver.

5. Packaging

5.1 Spooled wire 100 g, 250 g, 500 g, 1 kg;
Cartooned by 6 kg (100 g spools)
and 10 kg (others).

5.2 Spools and cartoons marked with solder type, diameter and batch number.

5.3 Bars cartooned by 25-30 kg; marked with solder type and batch number.

5.4 Rods - marked with solder type and batch number.